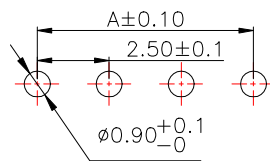
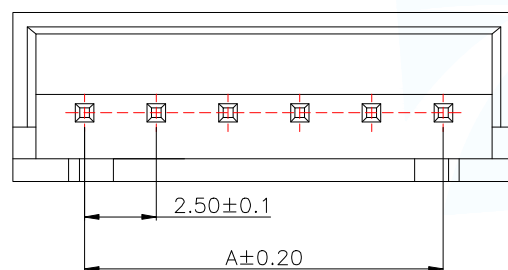


Part No	Pin	A	B
WAFER-XH2.54-2PZZ	2	2.50	7.50
WAFER-XH2.54-3PZZ	3	5.00	10.00
WAFER-XH2.54-4PZZ	4	7.50	12.50
WAFER-XH2.54-5PZZ	5	10.00	15.00
WAFER-XH2.54-6PZZ	6	12.50	17.50
WAFER-XH2.54-7PZZ	7	15.00	20.00
WAFER-XH2.54-8PZZ	8	17.50	22.50
WAFER-XH2.54-9PZZ	9	20.00	25.00
WAFER-XH2.54-10PZZ	10	22.50	27.50
WAFER-XH2.54-11PZZ	11	25.00	30.00
WAFER-XH2.54-12PZZ	12	27.50	32.50
WAFER-XH2.54-13PZZ	13	30.00	35.00
WAFER-XH2.54-14PZZ	14	32.50	37.50
WAFER-XH2.54-15PZZ	15	35.00	40.00
WAFER-XH2.54-16PZZ	16	37.50	42.50
WAFER-XH2.54-17PZZ	17	40.00	45.00
WAFER-XH2.54-18PZZ	18	42.50	47.50
WAFER-XH2.54-19PZZ	19	45.00	50.00
WAFER-XH2.54-20PZZ	20	47.50	52.50



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 100M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ} \sim +85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235 \pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求。

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡 80u"MIN
1	基座Wafer	PA66(UL94 V-0)	1	白色
序号	名称	材料	数量	备注

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: WAFER XH2.54MM 直针
DECIMALS:	ANGLES:		PAR WAFER-XH2.54-NPZZ
.X±0.20	±2'		DWN
.XX±0.10			CHKD
.XXX±0.05		APVD	SCALE 1:1 UNIT:MM
CUSTOMER COPY		SIZE: A4	SHEET: 1F1 REV: A